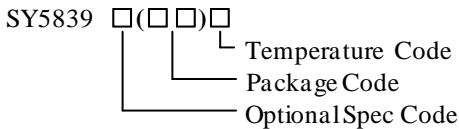


General Description

The SY5839 is a single stage Buck PFC controller targeting at LED lighting applications. It is a Buck converter operates in the quasi-resonant mode to achieve higher efficiency and keeps in constant on time operation to achieve high power factor. It adopts special design to achieve quick start up and reliable protection for safety requirement.

Ordering Information



Ordering Number	Package type	Note
SY5839ABC	SOT23-6	----

Features

- Valley turn-on of the MOSFET to achieve low switching loss
- Power factor >0.90 with single-stage conversion.
- Low start up current: 15μA typical
- Quick start up <500ms
- Reliable short LED and Open LED protection
- Power factor >0.90 with single-stage conversion
- RoHS Compliant and Halogen Free
- Compact package: SOT23-6

Applications

- LED lighting
- Down light
- Tube lamp
- PAR lamp
- Bulb lamp

Typical Applications

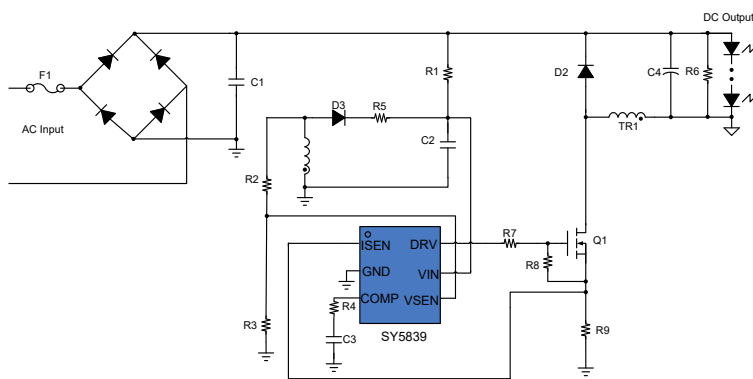


Figure 1. Schematic Diagram

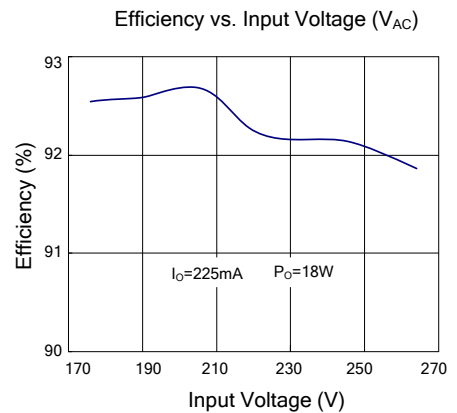
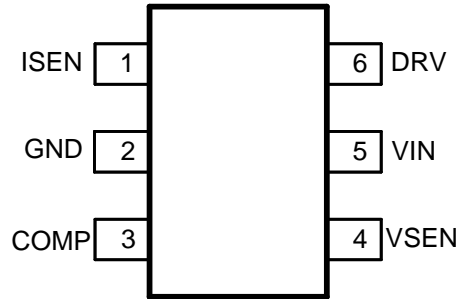


Figure 2. Efficiency vs Input Voltage

Pinout (top view)



(SOT23-6)

Top Mark: ZTxyz (device code: ZT, x=year code, y=week code, z=lot number code)

Pin Name	Pin Number	Pin Description
ISEN	1	Current sense pin. Connect this pin to the source of the switch. Connect the sense resistor across the source of the switch and the GND pin. (current sense resistor R_s : $I_o = \frac{1}{2} \times \frac{V_{REF}}{R_s}$).
GND	2	Ground pin
COMP	3	Loop compensation pin. Connect a RC network across this pin and ground to stabilize the control loop.
VSEN	4	Inductor current zero-crossing detection pin. This pin receives the auxiliary winding voltage by a resistor divider and detects the inductor current zero crossing point. This pin also provides over voltage protection and line regulation modification function simultaneously. If the voltage on this pin is above $V_{SEN,OVLP}$, the IC would enter over voltage protection mode. Good line regulation can be achieved by adjusting the upper resistor of the divider.
VIN	5	Power supply pin. This pin also provides output over voltage protection along with VSEN pin.
DRV	6	Gate drive pin. Connect this pin to the gate of MOSFET.

Absolute Maximum Ratings (Note 1)

VIN, DRV	-----	-0.3V~33V
Supply Current I _{VIN}	-----	15mA
VSEN	-----	-0.3V ~V _{IN} +0.3
I _{SEN} , COMP	-----	-0.3~3.6V
Power Dissipation, @ T _A = 25°C SOT23-6	-----	0.6W
Package Thermal Resistance (Note 2)		
SOT23-6, θ _{JA}	-----	170°C/W
SOT23-6, θ _{JC}	-----	130°C/W
Junction Temperature Range	-----	-40°C to 150°C
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-65°C to 150°C

Recommended Operating Conditions (Note 3)

VIN, DRV	-----	9.5V~27V
Junction Temperature Range	-----	-40°C to 125°C

Block Diagram

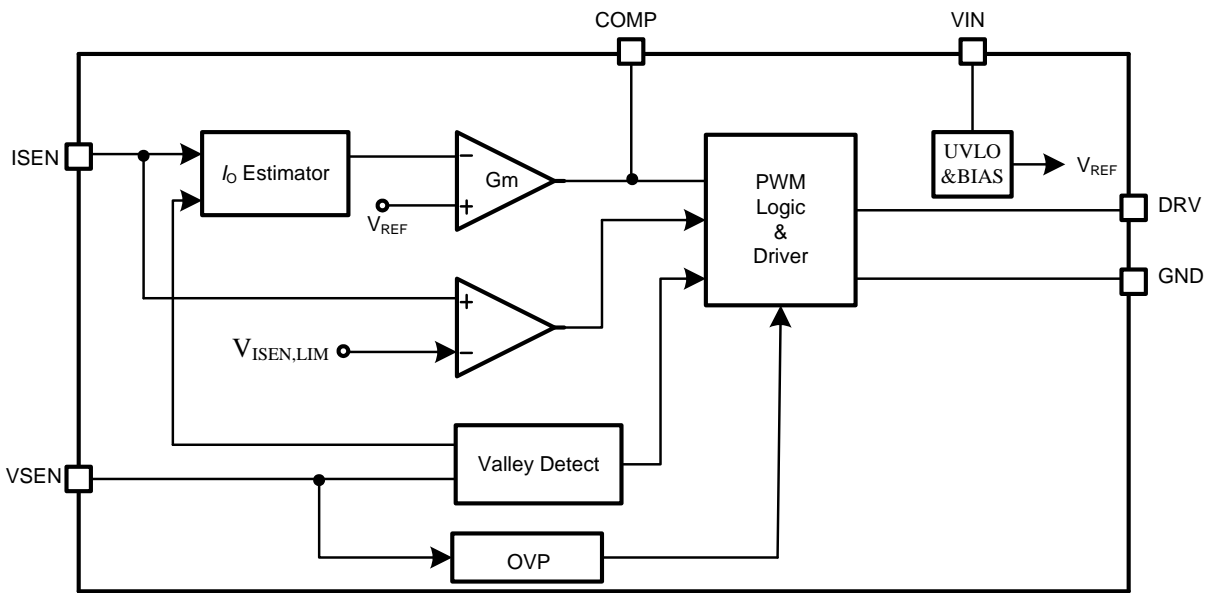


Figure3. Block Diagram

Electrical Characteristics

($V_{IN} = 12V$ (Note 3), $T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Power Supply Section						
VIN Turn-on Threshold	$V_{VIN,ON}$		22.5	25.3	27	V
VIN Turn-off Threshold	$V_{VIN,OFF}$		7.5	8.5	9.5	V
VIN OVP Voltage	$V_{VIN,OVP}$		27	30	33	V
Start up Current	I_{ST}	$V_{VIN} < V_{VIN,ON}$	12	15	28	μA
Shunt Current in OVP Mode	$I_{VIN,OVP}$	$V_{VIN} > V_{VIN,OVP}$	3.8	4.7	5.7	mA
Error Amplifier Section						
Internal Reference Voltage	V_{REF}		0.294	0.3	0.306	V
Current Sense Section						
Current Limit Voltage	$V_{ISEN,LIMIT}$		0.665	0.75	0.805	V
Protection Limit for TR Short	$V_{ISEN,EX}$		1.39	1.5	1.61	V
CC Feedforward Coefficient	K_2			0.1		
CC Feedforward Resistor	R_{K2}			340		Ω
COMP Section						
Pre-charge Value	$V_{COMP,ST}$			0.95		V
VSEN Pin Section						
VSEN Pin OVP Voltage Threshold	$V_{VSEN,OVP}$		1.43	1.5	1.57	V
Fast Start up Threshold	$V_{VSEN,ST}$			0.6		V
Gate Driver Section						
Gate Driver Voltage	V_{Gate}		9.5	11.7	13	V
Maximum Source Current	I_{SOURCE}			0.06		A
Minimum Sink Current	I_{SINK}			0.25		A
Max ON Time	$T_{ON,MAX}$	$V_{ISEN}=0V$	18.0	26.0	38.0	μs
Max OFF Time	$T_{OFF,MAX}$	$V_{FB}<0.6V$	135	200	255	μs
Blanking Time for ON Time	$T_{ON,BLK}$			350		ns
Blanking Time for OFF Time	$T_{OFF,BLK}$			1.6		μs
Maximum Switching Frequency	f_{MAX}			125		kHz
Thermal Section						
Thermal Shutdown Temperature	T_{SD}			150		C

Note 1: Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: Θ_{JA} is measured in the natural convection at $T_A = 25^\circ C$ on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2” x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

Note 3: Increase VIN pin voltage gradually higher than $V_{VIN,ON}$ voltage then turn down to 12V.

Operation

SY5839 is a constant current Buck PFC controller targeting at LED lighting applications.

High power factor is achieved by constant on time operation mode, with which the control scheme and the circuit structure are both simple.

Start up process is optimized inside SY5839, and quick start up (less than 500ms) is achieved without any additional circuit

In order to reduce the switching losses and improve EMI performance, Quasi-Resonant switching mode is applied, which means to turn on the power MOSFET at voltage valley; the start up current of SY5839 is rather small (15 μ A typically) to reduce the standby power loss further; the maximum switching frequency is clamped to 125kHz to reduce switching losses and improve EMI performance when the converter is operated at light load condition.

SY5839 provides reliable protections such as Short Circuit Protection (SCP), Open LED Protection (OLP), Over Temperature Protection (OTP), transformer shorted protection and power diode shorted protection, etc.

SY5839 is available with SOT23-6

Applications Information

Start up

After AC supply or DC BUS is powered on, the capacitor C_{VIN} across VIN and GND pin is charged up by BUS voltage through a start up resistor R_{ST} . Once V_{VIN} rises up to V_{VIN_ON} , the internal blocks start to work and PWM output is enabled.

The output voltage is feedback by VSEN pin, which is taken as V_{FB} . If V_{FBV} is lower than certain threshold V_{VSEN_ST} , which means the output voltage is not built up, V_{COMP} is pulled up to high clamped; if V_{FBV} is higher than V_{VSEN_ST} , V_{COMP} is under charge of the internal gain modulator.

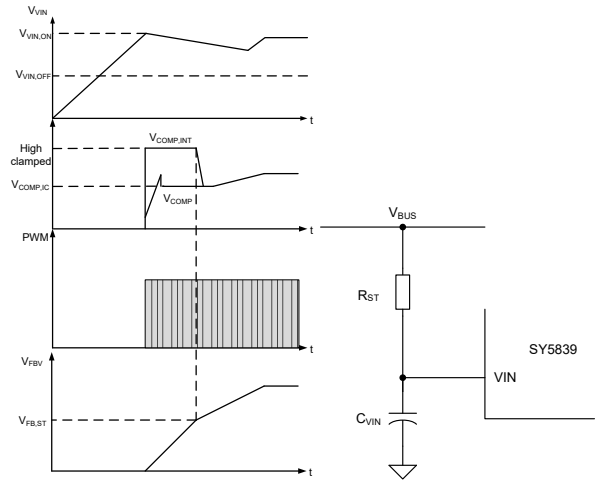


Fig. Start up

This operation is aimed to build up enough output voltage for auxiliary winding bias supply as quickly as possible. It is enabled only one time just when V_{VIN} is over V_{VIN_ON} .

V_{COMP} is pre-charged by internal current source to V_{COMP_IC} and hold at this level until fast start up process is finished.

The start up resistor R_{ST} and C_{VIN} are designed by rules below:

(a) Preset start-up resistor R_{ST} , make sure that the current through R_{ST} is larger than I_{ST} and smaller than I_{VIN_OVP}

$$\frac{V_{BUS}}{I_{VIN_OVP}} < R_{ST} < \frac{V_{BUS}}{I_{ST}}$$

Where V_{BUS} is the BUS line voltage.

(b) Select C_{VIN} to obtain an ideal start up time t_{ST} , and ensure the output voltage is built up at one time.

$$C_{VIN} = \frac{\left(\frac{V_{BUS}}{R_{ST}} - I_{ST}\right) \times t_{ST}}{V_{VIN_ON}}$$

(d) If the C_{VIN} is not big enough to build up the output voltage at one time. Increase C_{VIN} and decrease R_{ST} , go back to step (a) and redo such design flow until the ideal start up procedure is obtained.

Shut down

After AC supply or DC BUS is powered off, the energy stored in the BUS capacitor will be discharged. When the auxiliary winding can not supply enough energy to VIN pin, V_{VIN} will drop down. Once V_{VIN} is below V_{VIN-OFF}, the IC will stop working and V_{COMP} will be discharged to zero.

constant-current control

The switching waveforms are shown in wave form below. The output current I_{OUT} can be represented by,

$$I_{OUT} = \frac{I_{PK}}{2} \times \frac{t_{EFF}}{t_s}$$

Where I_{PK} is the peak current of the inductor; t_{EFF} is the effective time of inductor current rising and falling; t_s is the switching period.

I_{PK} and t_{EFF} can be detected by Source and VSEN pin, which is shown in Output current detection diagram. These signals are processed and applied to the negative input of the gain modulator. In static state, the positive and negative inputs are equal.

$$V_{REF} = I_{PK} \times R_s \times \frac{t_{EFF}}{t_s}$$

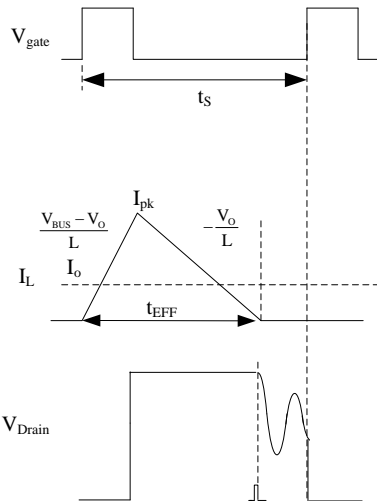


Fig. switching waveforms

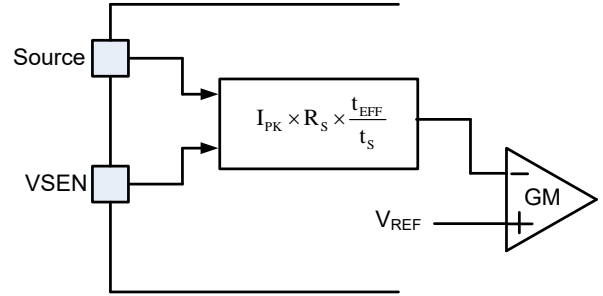


Fig. Output current detection diagram

Finally, the output current I_{OUT} can be represented by

$$I_{OUT} = \frac{V_{REF}}{R_s \times 2}$$

Where V_{REF} is the internal reference voltage; R_s is the current sense resistor.

V_{REF} is internal constant parameters, I_{OUT} can be programmed by R_s.

$$R_s = \frac{V_{REF}}{I_{OUT} \times 2}$$

Quasi-Resonant Operation

QR mode operation provides low turn-on switching losses for Buck converter.

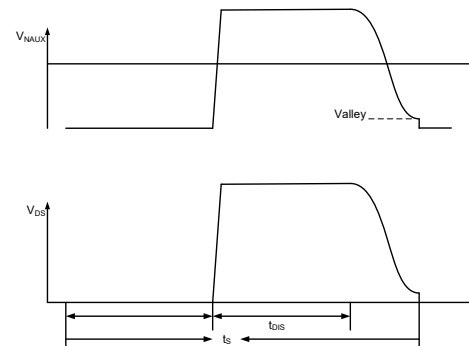


Fig. QR mode operation

The voltage across drain and source of the MOSFET is reflected by the auxiliary winding of the Buck transformer. VSEN pin detects the voltage across the auxiliary winding by a resistor divider. When the voltage across drain and source of the MOSFET is at voltage valley, the MOSFET would be turned on.

Over Voltage Protection (OVP) & Open LED Protection (OLP)

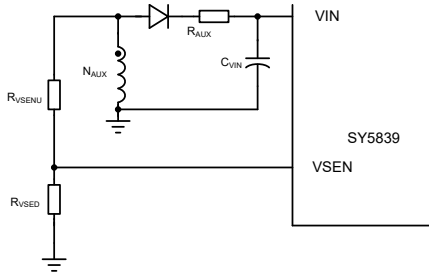


Fig. OVP&OLP

The output voltage is reflected by the auxiliary winding voltage, and both VSEN pin and VIN pin provide over voltage protection function. When the load is null or large transient happens, the output voltage will exceed the rated value. When V_{VIN} exceeds $V_{VIN,OV}$ or V_{VSEN} exceeds $V_{VSEN,OV}$, the over voltage protection is triggered and the IC will discharge V_{VIN} by an internal current source $I_{VIN,OV}$. Once V_{VIN} is below $V_{VIN,OFF}$, the IC will shut down and be charged again by BUS voltage through start up resistor. If the over voltage condition still exists, the system will operate in hiccup mode.

Thus, the turns of the auxiliary winding N_{AUX} and the resistor divider is related with the OVP function.

$$\frac{V_{SEN_OV}}{V_{OV}} = \frac{N_{AUX}}{N} \times \frac{R_{VSEND}}{R_{VSENU} + R_{VSEND}}$$

$$\frac{V_{VIN_OV}}{V_{OV}} \geq \frac{N_{AUX}}{N}$$

Where V_{OV} is the output over voltage specification; R_{VSENU} and R_{VSEND} compose the resistor divider. The turns ratio of N to N_{AUX} and the ratio of R_{VSENU} to R_{VSEND} could be induced from equation above.

Short Circuit Protection (SCP)

When the output is shorted to ground, the output voltage is clamped to zero. The voltage of the auxiliary winding is proportional to the output winding, so valley signal cannot be detected by VSEN. Without valley detection, MOSFET cannot be turned ON until maximum off time $t_{OFF,MAX}$ is matched. If MOSFET is turned ON by $t_{OFF,MAX}$ 64 times continuously, IC will be shut down and enter into hiccup mode.

If the output voltage is not low enough to disable valley detection in short condition, V_{VIN} will drop down without auxiliary winding supply. Once V_{VIN} is below $V_{VIN,OFF}$,

the IC will shut down and be charged again by the BUS voltage through the start up resistor. If the short circuit condition still exists, the system will operate in hiccup mode.

Line regulation modification

The IC provides line regulation modification function to improve line regulation performance.

Due to the sample delay of ISEN pin and other internal delay, the output current increases with increasing input BUS line voltage. A small compensation voltage $\Delta V_{ISEN,C}$ is added to ISEN pin during ON time to improve such performance. This $\Delta V_{ISEN,C}$ is adjusted by the upper resistor of the divider connected to VSEN pin.

$$\Delta V_{ISEN,C} = (V_{BUS} - V_{OUT}) \times \frac{N_{AUX}}{N} \times \frac{K_2 \times (R_{K2} + R_{ISEN,C})}{R_{VSEN,U}}$$

Where R_{VSENU} is the upper resistor of the divider; k_2 is an internal constant as the modification coefficient; R_{k2} is an internal feed-forward resistor; auxiliary resistor $R_{ISEN,C}$ can be added to enhance feed-forward effects.

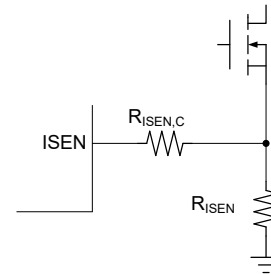


Fig. feed-forward resistor

Single fault design

If VSEN pin is shorted to GND pin or floating, valley detection is failed, which is similar to SLP, the system will operate in hiccup mode.

If the transformer or the diode is shorted, V_{ISEN} will exceed $V_{ISEN,EX}$, and the system will operate in hiccup mode.

Thermal fold back design

If IC junction temperature rises over T_{FB} , the output current will be decreased to regulate the junction temperature around T_{FB} . If the junction temperature is over T_{SD} , IC will be shut down and won't recover unless the junction temperature drops below T_{FB} .

Power Device Design

MOSFET and Diode

When the operation condition is with maximum input voltage and full load, the voltage stress of MOSFET and output power diode is maximized;

$$V_{MOS_DS_MAX} = \sqrt{2}V_{AC_MAX}$$

$$V_{D_R_MAX} = \sqrt{2}V_{AC_MAX}$$

Where V_{AC_MAX} is maximum input AC RMS voltage.

When the operation condition is with minimum input voltage and full load, the current stress of MOSFET and power diode is maximized.

Inductor (L)

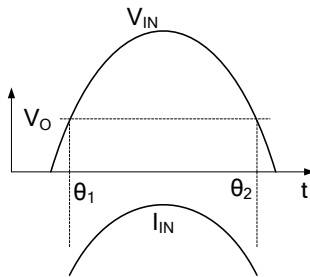


Fig. input waveforms

The power is transferred from AC input to output only when the input voltage is larger than output voltage in Buck converter. The input voltage and inductor current waveforms are shown in above, where θ_1 and θ_2 are the time that input voltage is equal to output voltage.

In Quasi-Resonant mode, each switching period cycle t_s consists of three parts: current rising time t_1 , current falling time t_2 and quasi-resonant time t_3 shown in wave form below.

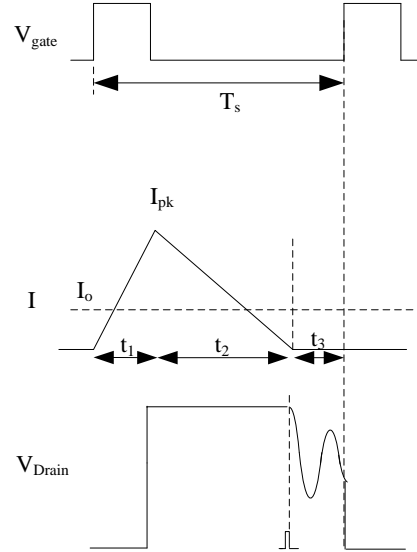


Fig. switching waveforms

The system operates in the constant on time mode to achieve high power factor. The ON time increases with the input AC RMS voltage decreasing and the load increasing. When the operation condition is with minimum input AC RMS voltage and full load, the ON time is maximized. On the other hand, when the input voltage is at the peak value, the OFF time is maximized. Thus, the minimum switching frequency f_{S_MIN} happens at the peak value of input voltage with minimum input AC RMS voltage and maximum load condition; Meanwhile, the maximum peak current through MOSFET and the transformer happens.

Once the minimum frequency f_{S_MIN} is set, the inductance of the transformer could be Calculated. The design flow is shown as below:

(a) Preset minimum frequency f_{S_MIN}

(b) Compute relative t_s , t_1

$$t_s = \frac{1}{f_{S_MIN}}$$

$$t_1 = \frac{t_s \times (V_{OUT} + V_{DF})}{(\sqrt{2}V_{AC_MIN} + V_{DF})}$$

$$t_2 = t_s - t_1$$

Where V_{DF} is the forward voltage of the diode

(c) Design inductance L

$$\theta_1 = \arcsin\left(\frac{V_{OUT}}{\sqrt{2}V_{AC_MIN}}\right) \times \frac{1}{\pi} \times \frac{1}{2 \times f_{AC}}$$

$$\theta_2 = \frac{1}{2 \times f_{AC}} - \theta_1$$

$$L = \frac{\eta \times f_{AC} \times V_{OUT} \times t_1}{P_{OUT}} \times [\sqrt{2}V_{AC_MIN} \times \frac{\cos(2\pi f_{AC} \times \theta_1) - \cos(2\pi f_{AC} \times \theta_2)}{2\pi f_{AC}} - V_{OUT}(\theta_2 - \theta_1)]$$

Where η is the efficiency; P_{OUT} is rated full load power;

(d) compute inductor maximum peak current $I_{L_PK_MAX}$.

$$I_{L_PK_MAX} = \frac{(\sqrt{2}V_{AC_MIN} - V_{OUT}) \times t_1}{L}$$

Where $I_{L_PK_MAX}$ is maximum inductor peak current ;

(e) compute RMS current of the inductor

$I_{L_RMS_MAX}$ is Inductor RMS current of whole AC period

$$I_{L_RMS_MAX} = \frac{t_1}{\sqrt{3} \times L} \sqrt{V_{AC_MIN}^2 + V_{OUT}^2 - \frac{4\sqrt{2}V_{AC_MIN} \times V_{OUT}}{\pi}}$$

(f) compute RMS current of the MOSFET

$$I_{L_RMS_MAX} = \sqrt{\frac{t_1}{3t_s} \times \frac{t_1}{L} \sqrt{V_{AC_MIN}^2 + V_{OUT}^2 - \frac{4\sqrt{2}V_{AC_MIN} \times V_{OUT}}{\pi}}}$$

Inductor design (N, N_{AUX})

The parameters below are necessary:

Necessary parameters	
Inductance	L
inductor maximum current	$I_{L_PK_MAX}$
inductor maximum RMS current	$I_{L_RMS_MAX}$

The design rules are as followed:

(a) Select the magnetic core style, identify the effective area A_e .

(b) Preset the maximum magnetic flux ΔB

$$\Delta B = 0.22 \sim 0.26 T$$

(c) Compute primary turn N

$$N = \frac{L_M \times I_{L_PK_MAX}}{\Delta B \times A_e}$$

(d) compute auxiliary turn N_{AUX}

$$N_{AUX} = N \times \frac{V_{VIN}}{V_{OUT}}$$

Where V_{VIN} is the working voltage of VIN pin.

(e) Select an appropriate wire diameter with $I_{L_RMS_MAX}$, select appropriate wire to make sure the current density ranges from 4A/mm² to 10A/mm².

(f) If the winding area of the core and bobbin is not enough, reselect the core style, go to (a) and redesign the transformer until the ideal transformer is achieved.

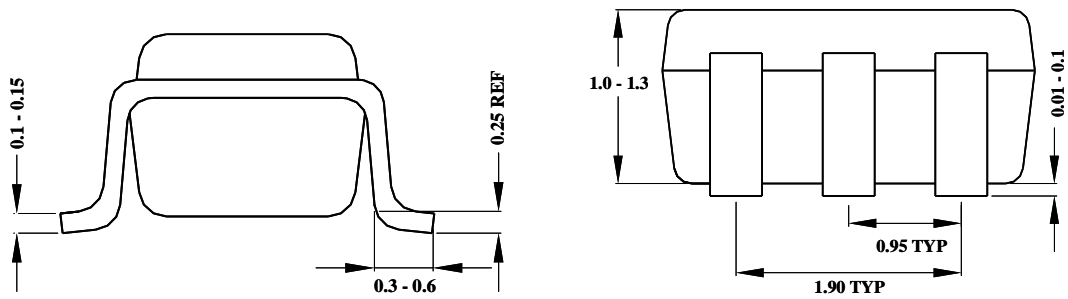
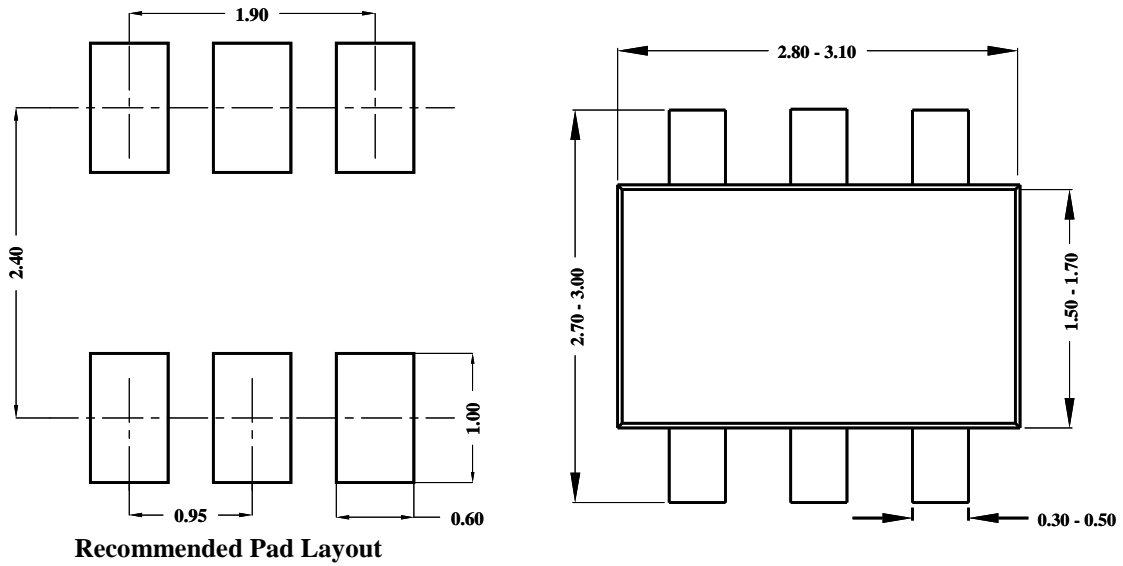
Output capacitor C_{OUT}

Preset the output current ripple ΔI_{OUT} , C_{OUT} is induced by

$$C_{OUT} = \frac{\sqrt{\left(\frac{2I_{OUT}}{\Delta I_{OUT}}\right)^2 - 1}}{4\pi f_{AC} R_{LED}}$$

Where I_{OUT} is the rated output current; ΔI_{OUT} is the demanded current ripple; f_{AC} is the input AC supply frequency; R_{LED} is the equivalent series resistor of the LED load.

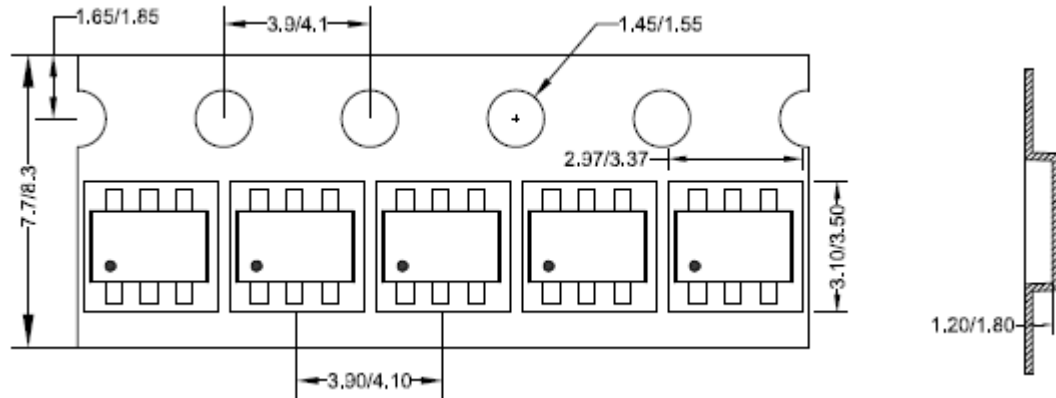
SOT23-6 Package outline & PCB layout design



**Notes: All dimensions are in millimeters.
All dimensions don't include mold flash & metal burr.**

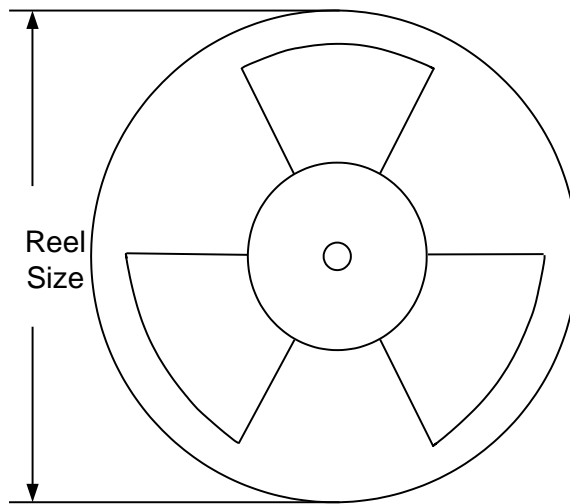
Taping & Reel Specification

1. Taping orientation for packages (SOT23-6)



Feeding direction →

2. Carrier Tape & Reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SOT23-6	8	4	7"	280	160	3000

IMPORTANT NOTICE

- 1. Right to make changes.** Silergy and its subsidiaries (hereafter Silergy) reserve the right to change any information published in this document, including but not limited to circuitry, specification and/or product design, manufacturing or descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to Silergy's standard terms and conditions of sale.
- 2. Applications.** Application examples that are described herein for any of these products are for illustrative purposes only. Silergy makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Buyers are responsible for the design and operation of their applications and products using Silergy products. Silergy or its subsidiaries assume no liability for any application assistance or designs of customer products. It is customer's sole responsibility to determine whether the Silergy product is suitable and fit for the customer's applications and products planned. To minimize the risks associated with customer's products and applications, customer should provide adequate design and operating safeguards. Customer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Silergy assumes no liability related to any default, damage, costs or problem in the customer's applications or products, or the application or use by customer's third-party buyers. Customer will fully indemnify Silergy, its subsidiaries, and their representatives against any damages arising out of the use of any Silergy components in safety-critical applications. It is also buyers' sole responsibility to warrant and guarantee that any intellectual property rights of a third party are not infringed upon when integrating Silergy products into any application. Silergy assumes no responsibility for any said applications or for any use of any circuitry other than circuitry entirely embodied in a Silergy product.
- 3. Limited warranty and liability.** Information furnished by Silergy in this document is believed to be accurate and reliable. However, Silergy makes no representation or warranty, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. In no event shall Silergy be liable for any indirect, incidental, punitive, special or consequential damages, including but not limited to lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges, whether or not such damages are based on tort or negligence, warranty, breach of contract or any other legal theory. Notwithstanding any damages that customer might incur for any reason whatsoever, Silergy' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Standard Terms and Conditions of Sale of Silergy.
- 4. Suitability for use.** Customer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of Silergy components in its applications, notwithstanding any applications-related information or support that may be provided by Silergy. Silergy products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of a Silergy product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Silergy assumes no liability for inclusion and/or use of Silergy products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.
- 5. Terms and conditions of commercial sale.** Silergy products are sold subject to the standard terms and conditions of commercial sale, as published at <http://www.silergy.com/stdterms>, unless otherwise agreed in a valid written individual agreement specifically agreed to in writing by an authorized officer of Silergy. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Silergy hereby expressly objects to and denies the application of any customer's general terms and conditions with regard to the purchase of Silergy products by the customer.
- 6. No offer to sell or license.** Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights. Silergy makes no representation or warranty that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right. Information published by Silergy regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from Silergy under the patents or other intellectual property of Silergy.

For more information, please visit: www.silergy.com

© 2018 Silergy Corp.

All Rights Reserved.